No.	Item	Rating Value	Method of Examination
1	Resistance Value (at 25°C)	The resistance value should be within the specified tolerance.	After applying maximum operating voltage for 3 minutes and leaving for 2 hours at 25°C, measure by applying voltage of less than 1.5VDC (by a direct current of less than 10mA).
2	Adhesive Strength	There is no sign of electrode detachment.	Prepare soldered PTC to PCB *1 and add the force of 5.0N in the direction shown below. (PTC=POSISTOR®) PTC Glass Epoxy PCB
3	Vibration Resistance	There is no abnormal appearance after the test. Resistance change is less than ±20%. *2	Solder PTC to PCB *1 Vibration: 10-2000-10Hz (20 minutes) Max. Amplitude: 3.0mm Vibrate for 4 hours in each of 3 mutually perpendicular planes for a total of 12 hours. This test condition is according to "MIL-STD-202G Method 204D."
4	Resistance to Bending of Substance	There is no abnormal appearance after the test. Resistance change is less than ±20%. *2	Solder PTC on Test Board *1, and apply force on back side of Test Board shown below: Bending Speed: 1.0mm/s Bending Strength: 2.0mm Hold Time: 5±1 seconds Board Dimension: 100x40x1.6t mm Board Material: Glass Epoxy Force R230 Force R230 Force R230 Force
5	Solderability	Min. 95% electrode is covered with new solder. Resistance change is less than ±20%. *2	Solder Temp.: 230±5°C Solder: Sn63%/Pb37% (or 60%/40%) Soaking Time: 3±0.3 secs. Soaking Position: Until a whole electrode is soaked. This test condition is according to "IEC 60068-2-58 (2004)."
6	Soldering Heat Resistance	There is no abnormal appearance after the test. Resistance change is less than ±20%. *2	Solder Temp.: 260±5°C Solder: Sn63%/Pb37% (or 60%/40%) Flux: Containing less than 0.2wt% of chlorine. Soaking Time: 10±1 secs. Soaking Position: Until a whole electrode is soaked. Preheating: 150±5°C 3 mins This test condition is according to "IEC 60068-2-58 (2004)."

- *1 Above-mentioned soldering is done under the following conditions at our site.
 Glass-epoxy PC board

 - Standard land dimension
 - Standard solder paste
 - Standard solder profile

Above conditions are defined in Notice.

*2 Measure resistance after the test by applying voltage of less than 1.5VDC by a direct current of less than 10mA after product is left at 25±2°C for 2 hours.

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No.	Item	Rating Value	Method of Examination
7	Dry Heat Resistance	There is no abnormal appearance after the test. Resistance change is less than ±20%. *2 <tight tolerance="" type=""> Sensing temp. change is less than ±1°C.</tight>	Solder PTC to PCB *1 +150±3°C leave for 1000±12 hours
8	Cold Resistance		Solder PTC to PCB -40±3°C leave for 1000±12 hours
9	Damp Heat Resistance		Solder PTC to PCB *1 +85±3°C 80-85%RH leave for 1000±12 hours
10	Thermal Shock 1 *3		Solder PTC to PCB *1 Test Cycle: 300 cycles Step Temp. (°C) Time (minute) 1 -55+0, -3 30 2 +150+3, -0 30
11	Thermal Shock 2 *3		Solder PTC to PCB *1 Test Cycle: 1000 cycles Step Temp. (°C) Time (minute) 1 -55+0, -3 30 2 +125+3, -0 30
12	High Temperature Humidity Load		Solder PTC to PCB *1 85±3°C, 80-85%RH (in air), load max. operating voltage for 1000±12 hours
13	High Temperature Load		Solder PTC to PCB *1 85±3°C (in air), load max. operating voltage for 1000±12 hours.

^{*1} Above-mentioned soldering is done under the following conditions at our site.

- Glass-epoxy PC board
 Standard land dimension
- Standard solder paste
- Standard solder profile

Above conditions are defined in Notice.

^{*2} Measure resistance after the test by applying voltage of less than 1.5VDC by a direct current of less than 10mA after product is left at 25±2°C for 2 hours.

^{*3} We cannot guarantee the resistance change in Thermal Shock (No.10, 11) in a case of defective mounting.